

**Amendments to the Specification:**

Please delete the paragraph on page 5, lines 27-32 and replace with the following replacement paragraph:

On a first face 3 of substrate 2, module 1 has a contact area or metallisations or plates 4. Contact area 4 is that of a printed circuit for example. This printed circuit is obtained by laminating a layer of copper with thickness from 18 to 35 micrometres on the substrate. This copper layer is retained in position on first face 3 by a previously deposited adhesive. Substrate 2 with its copper layer is then generally engraved chemically to form the printed circuit [[4]].

Please delete the paragraph on page 7, lines 5-12 and replace with the following replacement paragraph:

According to a first embodiment, in order retain perforated mask 7 in position against second face 6 of substrate 2, this second face 6 has been coated beforehand with an adhesive means 8. In this case, adhesive means 8 may even be deposited before printed circuit [[4]] has been created. Moreover, adhesive means 8 may be applied to the entire second face 6, even the zones which correspond to the windows 9 of mask 7 (except at the positions of holes 5). Mask 7 is then laminated by rollers against adhesive means 8 on substrate 2.